

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	4.1mΩ@10V	100A

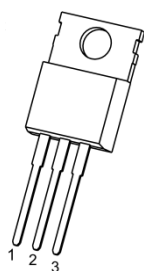
Feature

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation

Application

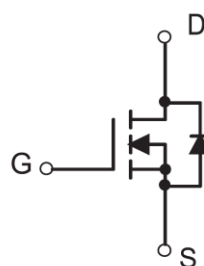
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Package

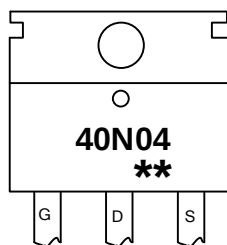


TO-220(1:G 2:D 3:S)

Circuit diagram



Marking



40N04 : Product code
** : Week code.



Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	100	A
Pulsed Drain Current	I_{DM}	400	A
Maximum Power Dissipation	P_D	90	W
Derating factor		0.6	W/°C
Single pulse avalanche energy (Note 5)	E_{AS}	670	mJ
Thermal Resistance, Junction-to-Case (Note 2)	$R_{\theta JC}$	1.67	°C/W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	°C

Electrical characteristics (T_A=25 °C, unless otherwise noted)

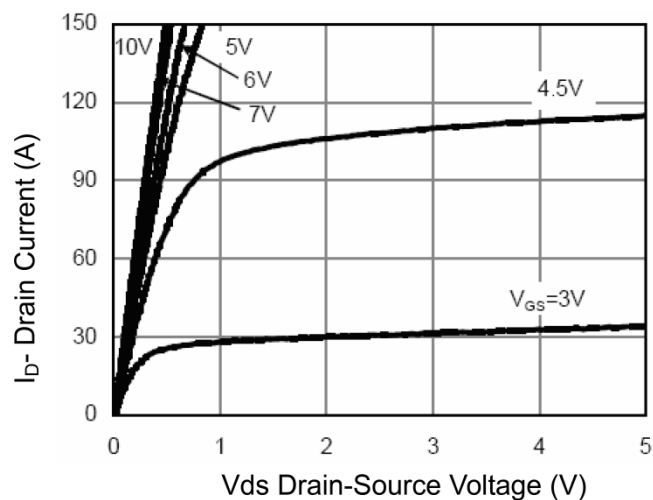
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.2	1.6	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	4.1	6	mΩ
		V _{GS} =4.5V, I _D =20A	-	5	7	
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =20A	15	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{ISS}	V _{DS} =20V, V _{GS} =0V, F=1.0MHz	-	-	5000	PF
Output Capacitance	C _{OSS}		-	-	900	PF
Reverse Transfer Capacitance	C _{RSS}		-	-	500	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =20V, R _L =1Ω V _{GS} =10V, R _G =3Ω	-	12	-	nS
Turn-on Rise Time	t _r		-	11	-	nS
Turn-Off Delay Time	t _{d(off)}		-	39	-	nS
Turn-Off Fall Time	t _f		-	12	-	nS
Total Gate Charge	Q _g	V _{DS} =20V, I _D =20A, V _{GS} =10V	-	61	-	nC
Gate-Source Charge	Q _{gs}		-	15.3	-	nC
Gate-Drain Charge	Q _{gd}		-	14.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =10A	-	-	1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 20A	-	-	45	nS
Reverse Recovery Charge	Q _{rr}	di/dt = 100A/μs (Note3)	-	-	50	nC

Notes:

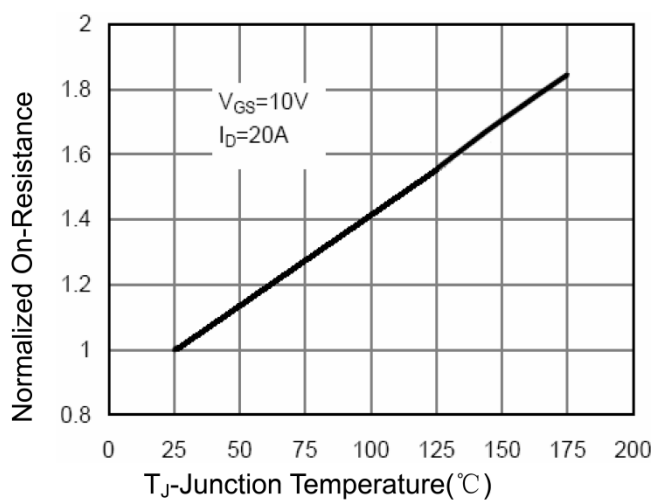
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_J=25^\circ C, V_{DD}=20V, V_G=10V, L=1mH, R_g=25\Omega, I_{AS}=36A$



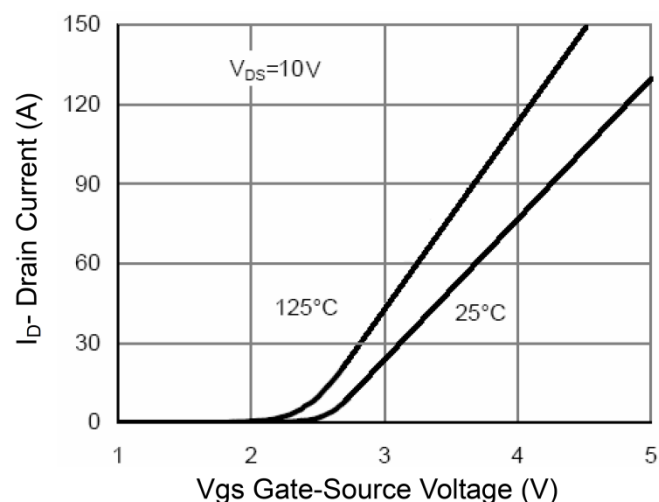
Typical Characteristics



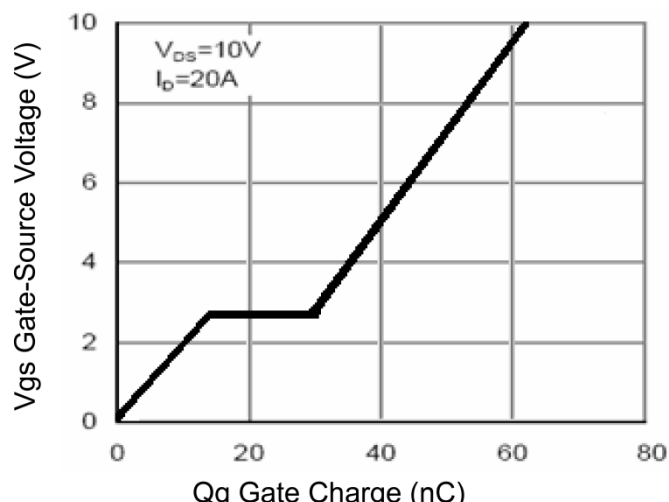
Output Characteristics



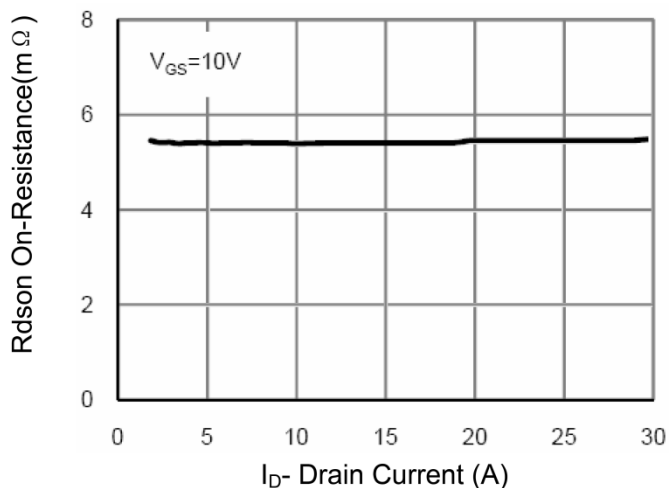
R_{dson} -Junction Temperature



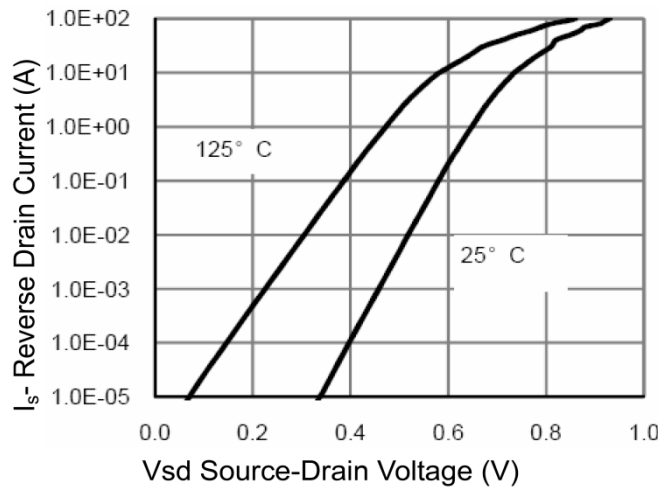
Transfer Characteristics



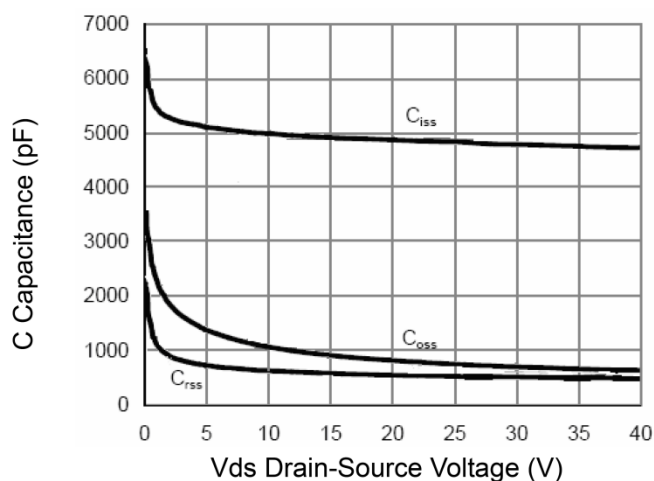
Gate Charge



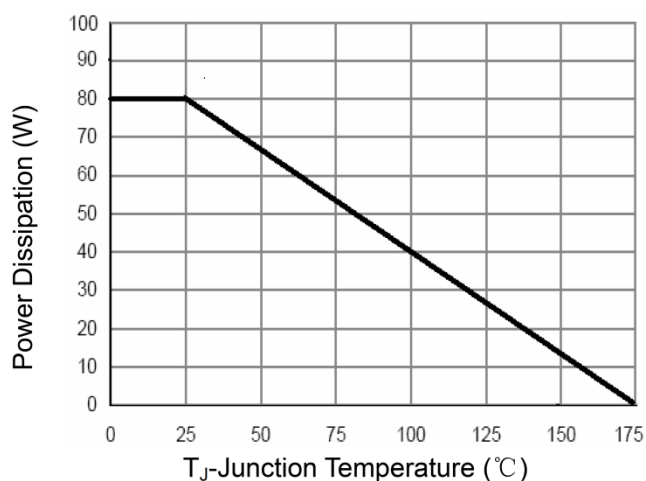
R_{dson} - Drain Current



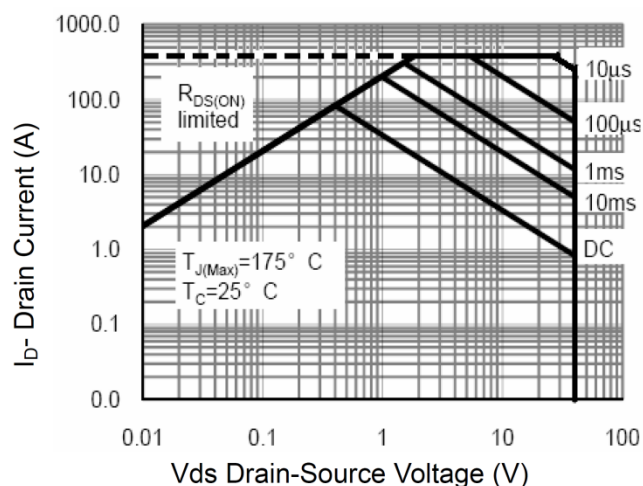
Source- Drain Diode Forward



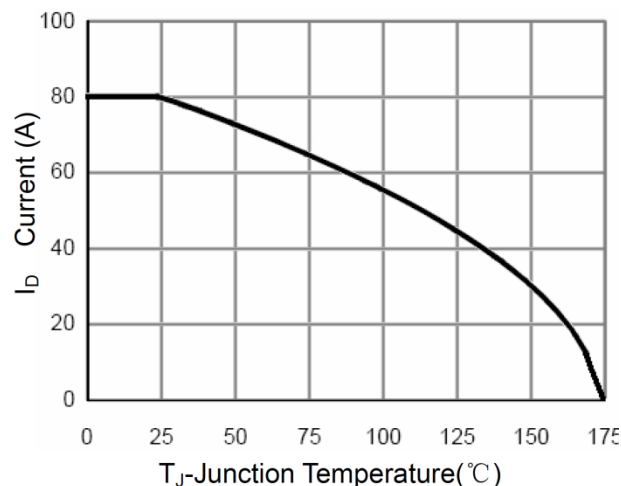
Capacitance vs Vds



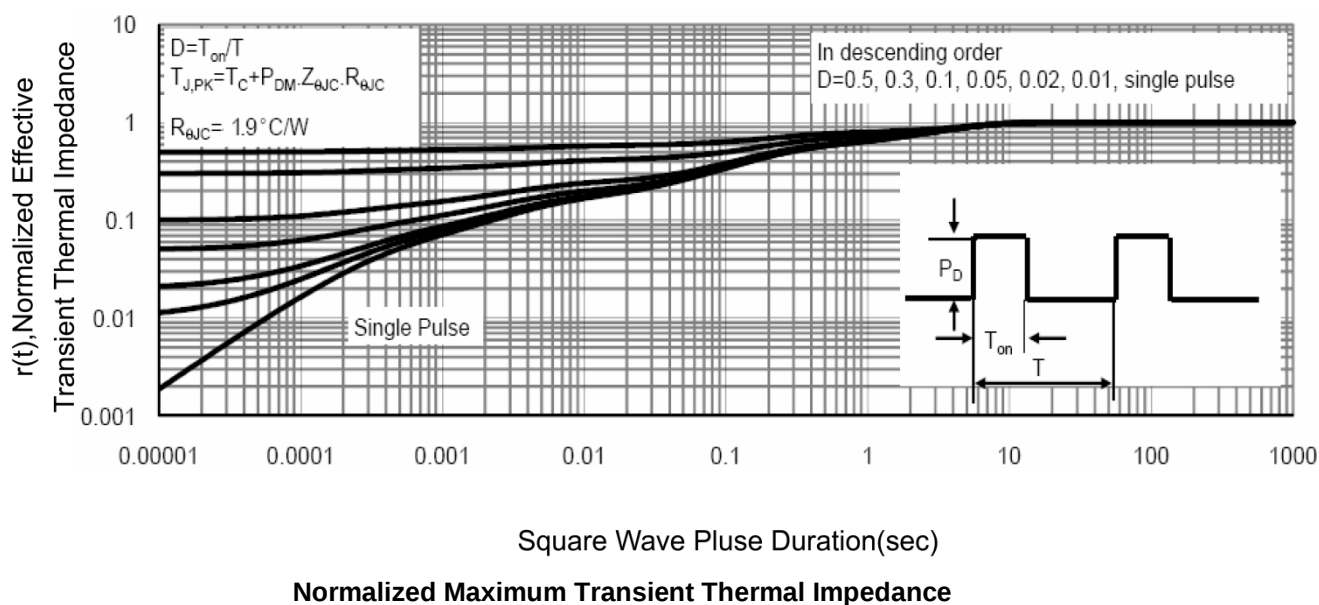
Power De-rating



Safe Operation Area

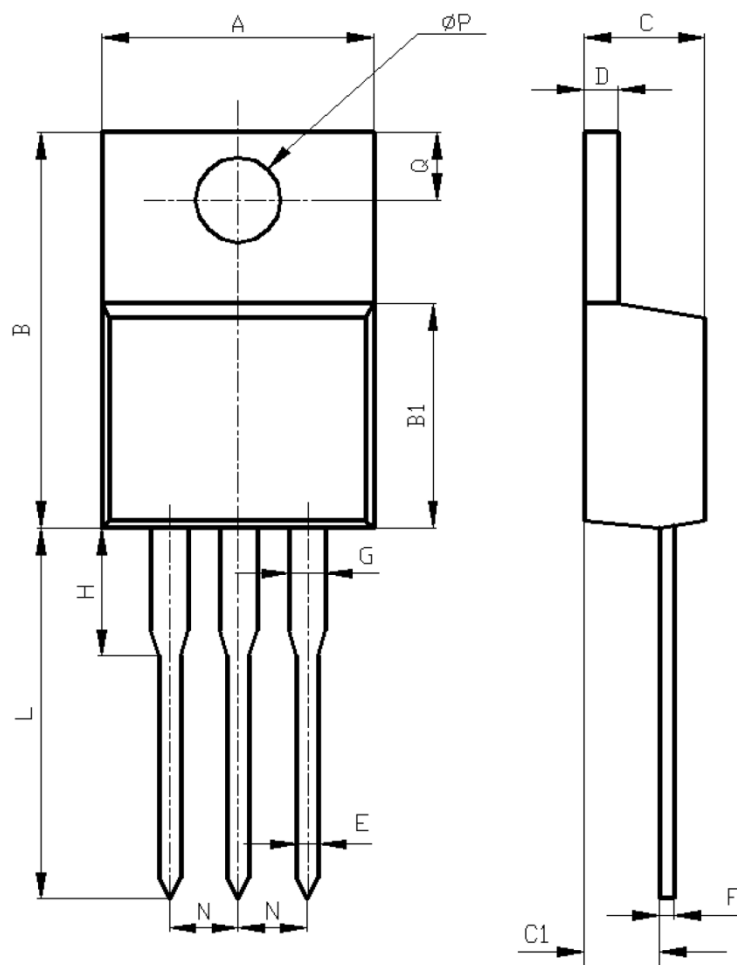


ID Current- Junction Temperature





TO-220-3L Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	10.1	10.5
B	15.2	15.6
B1	9	9.4
C	4.4	4.6
C1	2.4	3
D	1.2	1.4
E	0.7	0.9
F	0.4	0.6
G	1.17	1.37
H	3.3	3.8
L	13.1	13.7
N	2.34	2.74
Q	2.4	3
ØP	3.7	3.9